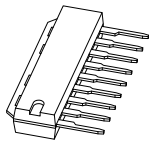


# SOT142-1

## plastic single in-line medium power package; 9 leads

8 February 2016 | Package information

## 1. Package summary

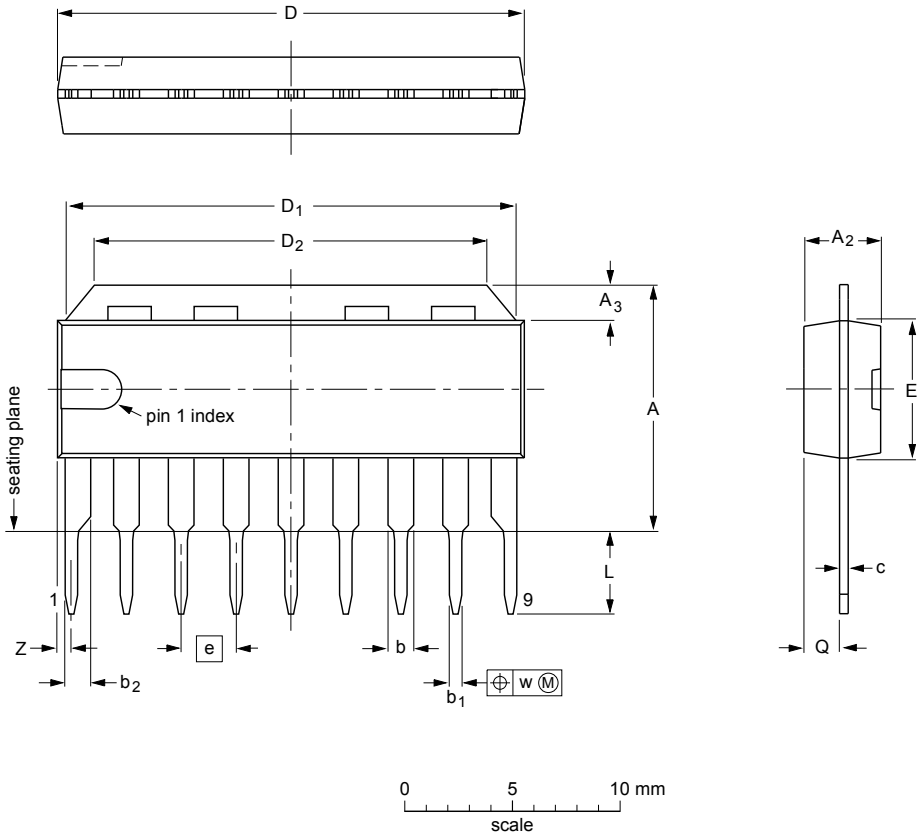
| | |
|---|---|
| **Terminal position code** | S (single) |
| **Package type descriptive code** | SIL9MP |
| **Package type industry code** | SIL9MP |
| **Package style descriptive code** | BCC (bottom chip carrier) |
| **Package style suffix code** | MP (medium power) |
| **Package body material type** | P (plastic) |
| **Mounting method type** | T (through-hole mount) |
| **Issue date** | 12-3-2003 |

**Table 1. Package summary**

| Symbol | Parameter | | Min | Typ | Nom | Max | Unit |
|---|---|---|---|---|---|---|---|
| D | package length | | 21.4 | - | 21.6 | 21.8 | mm |
| E | package width | | 6.2 | - | 6.35 | 6.48 | mm |
| A | seated height | | 11 | - | 12 | 12 | mm |
| $A_2$ | package height | | [tbd] | - | 3.55 | 3.7 | mm |
| $n_2$ | actual quantity of termination | | - | - | 9 | - | |

## 2. Package outline

**SIL9MP: plastic single in-line medium power package; 9 leads** **SOT142-1**




**DIMENSIONS (mm are the original dimensions)**

| UNIT | A | $A_2$ max. | $A_3$ | b | $b_1$ | $b_2$ | c | D(1) | $D_1$ | $D_2$ | E(1) | e | L | Q | w | Z(1) max. |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| mm | 12<br>11 | 3.7 | 1.8<br>1.4 | 1.40<br>1.14 | 0.67<br>0.50 | 1.40<br>1.14 | 0.48<br>0.38 | 21.8<br>21.4 | 21.4<br>20.7 | 18.6<br>18.2 | 6.48<br>6.20 | 2.54 | 3.9<br>3.4 | 1.75<br>1.55 | 0.25 | 1 |

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|---|---|---|---|---|---|---|
| | IEC | JEDEC | JEITA | | | |
| SOT142-1 | | | | | | ~~97-12-16~~<br>03-03-12 |

**Fig. 1. Package outline SIL9MP (SOT142-1)**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# 3. Legal information

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